

Dual N-Channel Logic Level Enhancement Mode Power MOSFET

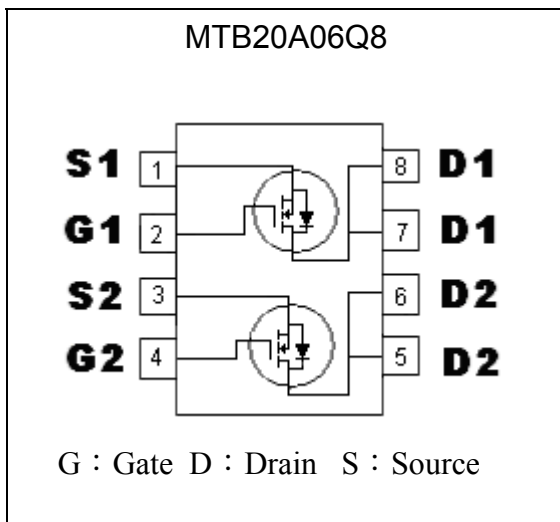
MTB20A06Q8

BV_{DSS}	60V
I_D@V_{GS}=10V, T_A=25°C	6A
I_D@V_{GS}=10V, T_C=25°C	8.5A
R_{DS(ON)}@V_{GS}=10V, I_D=6A	15.4 mΩ (typ)
R_{DS(ON)}@V_{GS}=4.5V, I_D=5A	16.3 mΩ (typ)

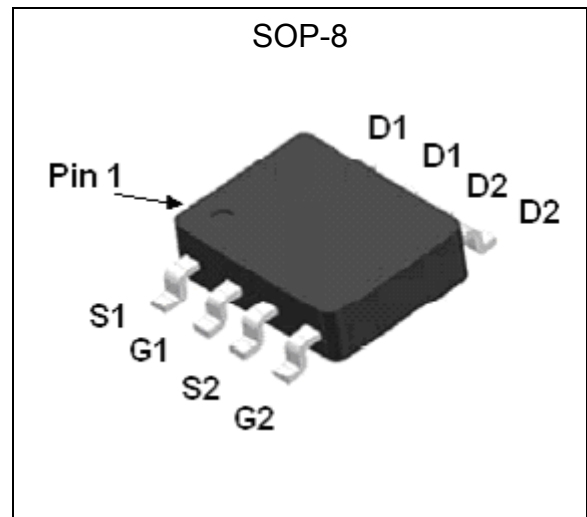
Features

- Single Drive Requirement
- Low On-resistance
- Fast Switching Characteristic
- Pb-free & halogen-free package

Symbol

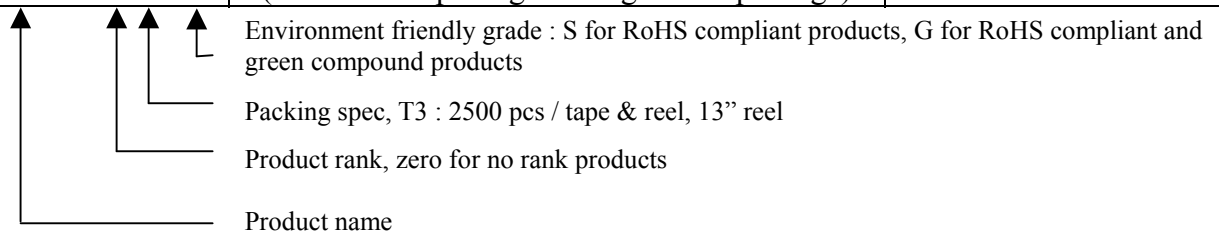


Outline



Ordering Information

Device	Package	Shipping
MTB20A06Q8-0-T3-G	SOP-8 (Pb-free lead plating & halogen-free package)	2500 pcs / Tape & Reel





Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current (Note 2)	I_{DSM}	$T_A=25^{\circ}\text{C}, V_{GS}=10\text{V}$	6.0
		$T_A=70^{\circ}\text{C}, V_{GS}=10\text{V}$	4.8
Continuous Drain Current	I_D	$T_C=25^{\circ}\text{C}, V_{GS}=10\text{V}$	8.5
		$T_C=100^{\circ}\text{C}, V_{GS}=10\text{V}$	6.0
Pulsed Drain Current (Note 3)	I_{DM}	50	A
Avalanche Current	I_{AS}	23	
Avalanche Energy @ $L=0.1\text{mH}, I_D=23\text{A}, R_G=25\Omega$	E_{AS}	26.5	
Power Dissipation for Dual Operation	P_{DSM}	2 (Note 2)	
Power Dissipation for Single Operation		1.6 (Note 2)	
		0.9 (Note 2)	
Power Dissipation	P_D	$T_C=25^{\circ}\text{C}$	3.75
		$T_C=100^{\circ}\text{C}$	1.88
Operating Junction and Storage Temperature	T_j, T_{stg}	$-55\sim+175$	$^{\circ}\text{C}$

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	$R_{th,j-c}$	40	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-ambient, max, dual operation	$R_{th,j-a}$	62.5	
Thermal Resistance, Junction-to-ambient, max, single operation		78 (Note 2)	
		135 (Note 3)	

- Note : 1. The power dissipation P_D is based on $T_{j(MAX)}=175^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in²FR-4 board with 2 oz. copper, in a still air environment with $T_A=25^{\circ}\text{C}$, $t \leq 10\text{s}$. $135^{\circ}\text{C}/\text{W}$ when mounted on a minimum pad of 2 oz. copper. The power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.
3. Pulse width limited by junction temperature $T_{j(MAX)}=175^{\circ}\text{C}$. Ratings are based on low duty cycles to keep initial $T_j=25^{\circ}\text{C}$.

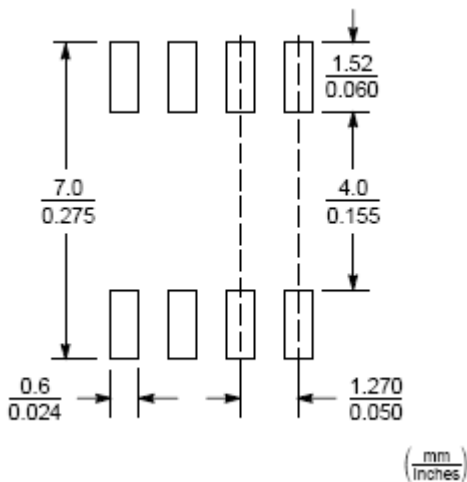
Characteristics ($T_j=25^{\circ}\text{C}$, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	60	-	-	V	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$
$V_{GS(th)}$	1.0	-	2.5	V	$V_{DS} = V_{GS}, I_D=250\mu\text{A}$
G_{FS}	-	16	-	S	$V_{DS} = 5\text{V}, I_D=6\text{A}$
I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 20\text{V}$
I_{DSS}	-	-	1	μA	$V_{DS} = 48\text{V}, V_{GS} = 0\text{V}$
	-	-	25		$V_{DS} = 48\text{V}, V_{GS} = 0\text{V}, T_j=55^{\circ}\text{C}$

*R _{DS(ON)}	-	15.4	20	mΩ	V _{GS} =10V, I _D =6A
	-	16.3	25		V _{GS} =4.5V, I _D =5A
Dynamic					
Q _g (V _{GS} =10V) *1, 2	-	40.4	-	nC	I _D =6A, V _{DS} =48V, V _{GS} =10V
Q _g (V _{GS} =4.5V) *1, 2	-	20.1	-		
Q _{gs} *1, 2	-	6.3	-		
Q _{gd} *1, 2	-	7.2	-		
C _{iss}	-	2400	-	pF	V _{GS} =0V, V _{DS} =25V, f=1MHz
C _{oss}	-	107	-		
C _{rss}	-	91	-		
t _{d(ON)} *1, 2	-	14.8	-	ns	V _{DS} =30V, I _D =6A, V _{GS} =10V, R _G =3.3 Ω
t _r *1, 2	-	16.2	-		
t _{d(OFF)} *1, 2	-	49	-		
t _f *1, 2	-	7.2	-		
R _g	-	1.5	-	Ω	V _{GS} =15mV, V _{DS} =0V, f=1MHz
Source-Drain Diode Ratings and Characteristics					
V _{SD} *1	-	0.78	1.2	V	I _F =6A, V _{GS} =0V
t _{rr}	-	15.4	-	ns	I _F =6A, dI _F /dt=100A/μs
Q _{rr}	-	11	-	nC	

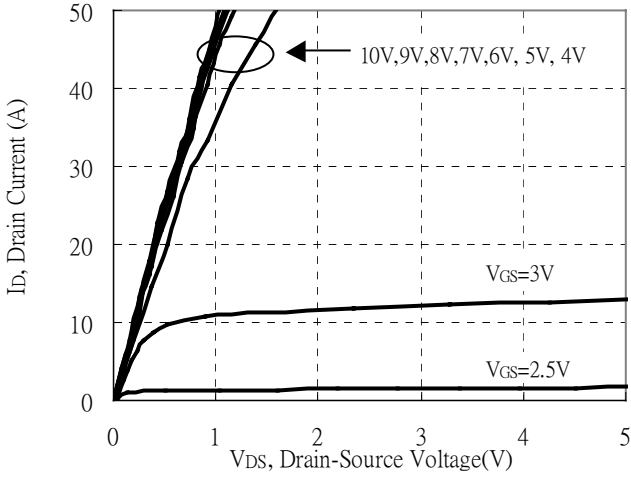
Note : *1.Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%
 *2.Independent of operating temperature
 *3.Pulse width limited by maximum junction temperature.

Recommended Soldering Footprint

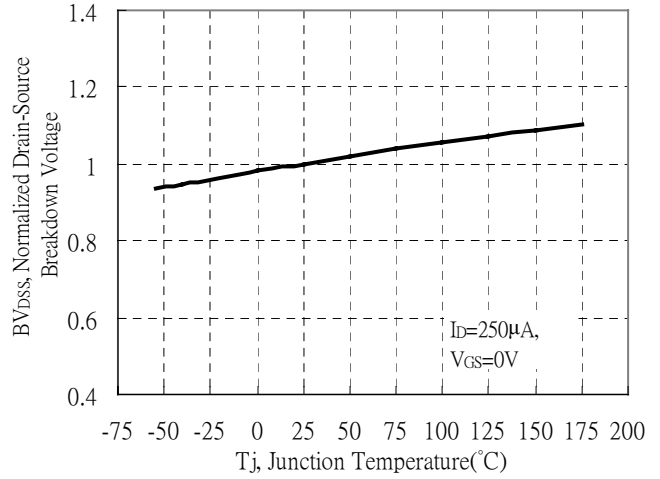


Typical Characteristics

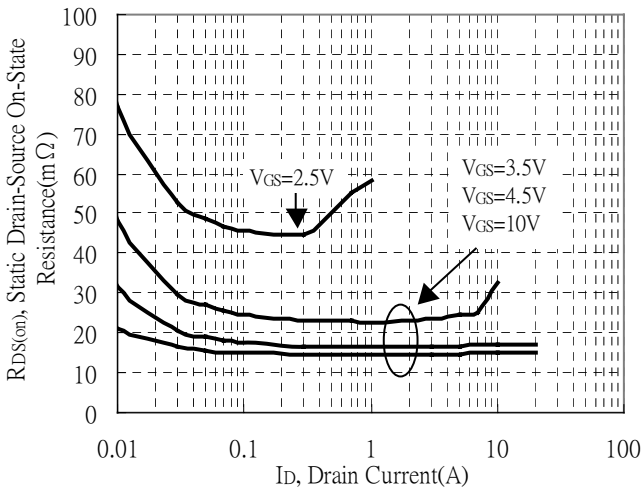
Typical Output Characteristics



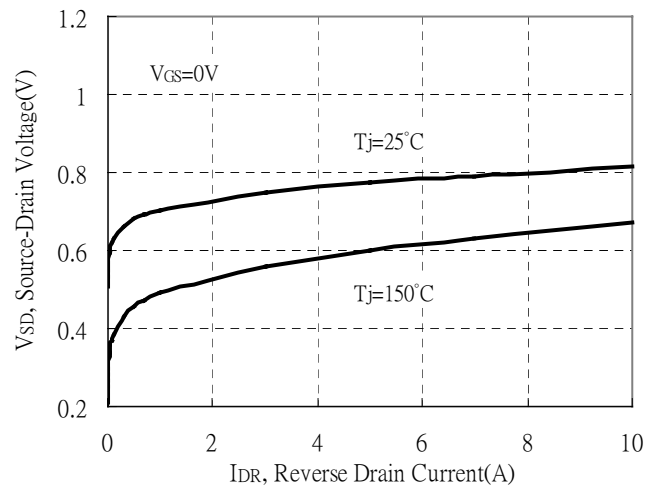
Brekdown Voltage vs Ambient Temperature



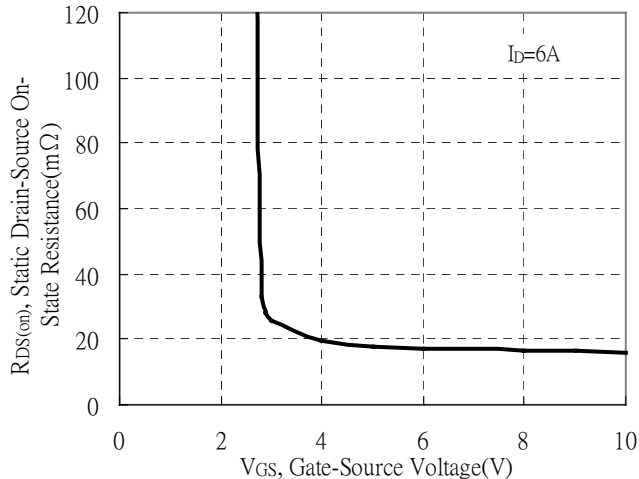
Static Drain-Source On-State resistance vs Drain Current



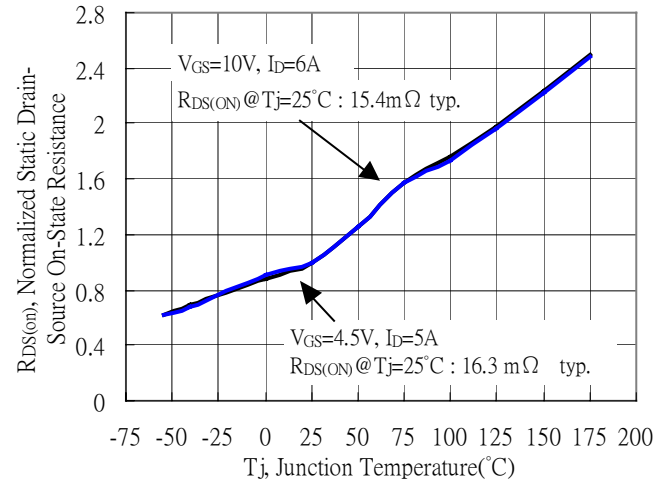
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

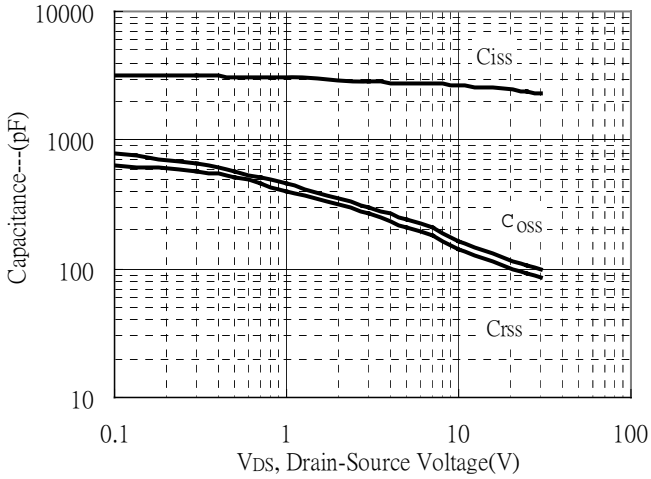


Drain-Source On-State Resistance vs Junction Temperature

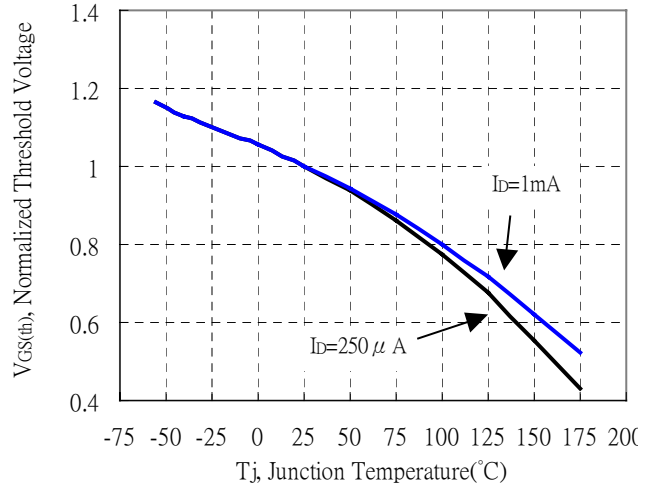


Typical Characteristics(Cont.)

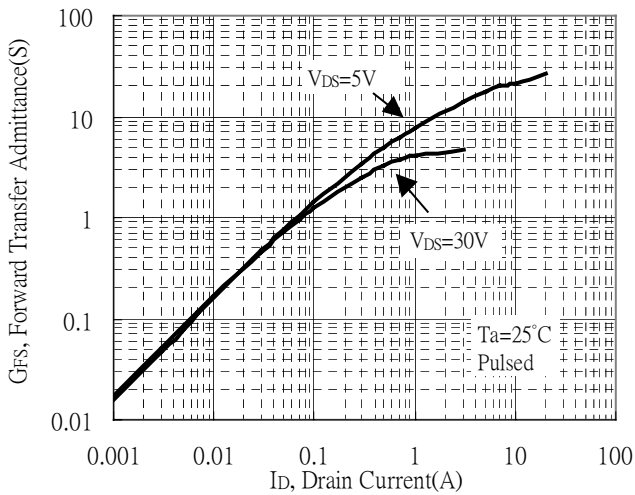
Capacitance vs Drain-to-Source Voltage



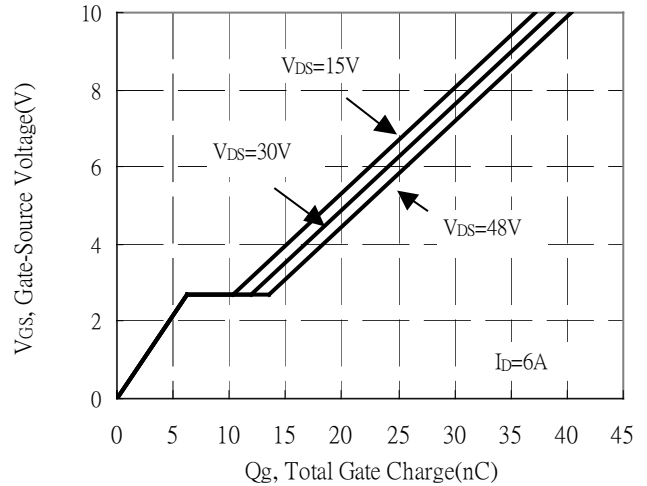
Threshold Voltage vs Junction Temperature



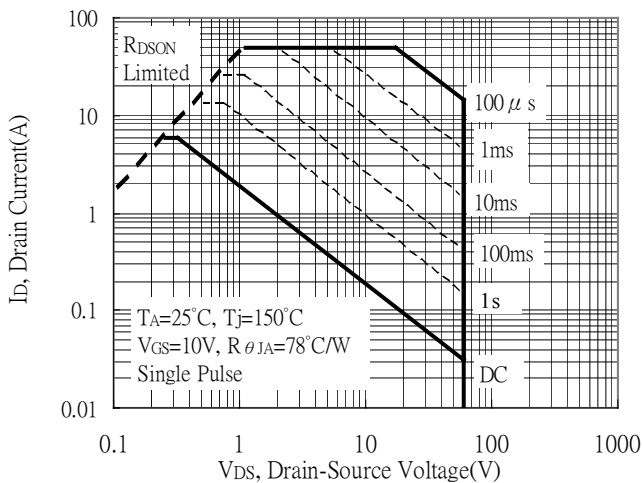
Forward Transfer Admittance vs Drain Current



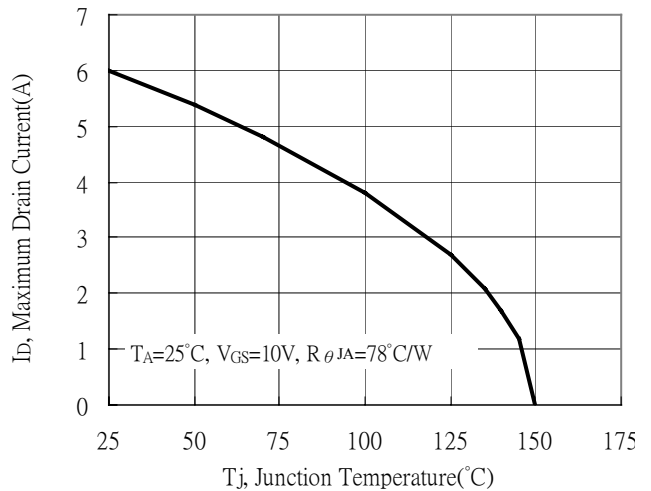
Gate Charge Characteristics



Maximum Safe Operating Area



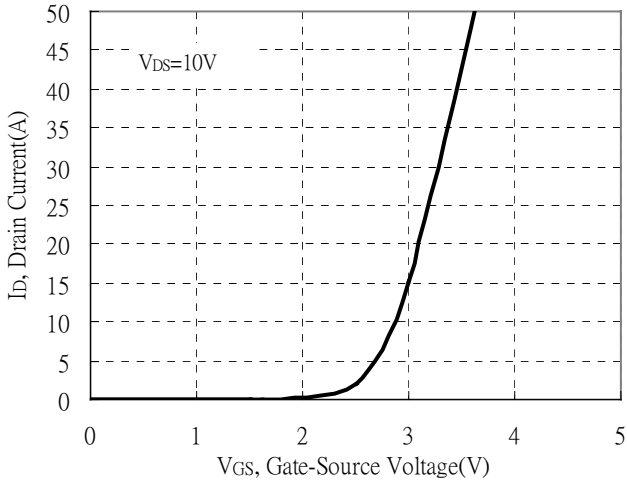
Maximum Drain Current vs Junction Temperature



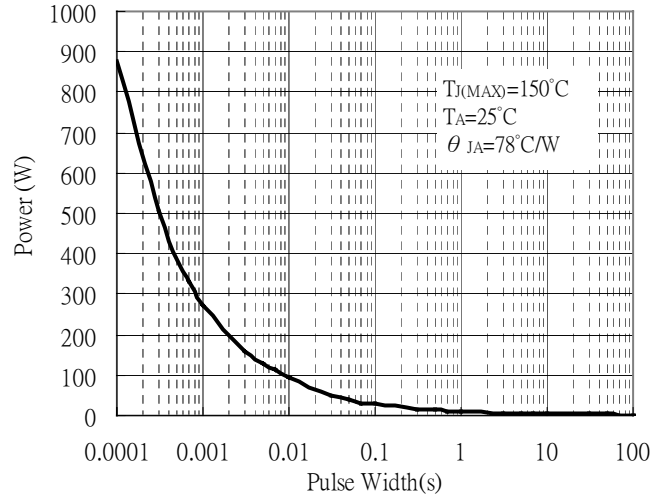


Typical Characteristics(Cont.)

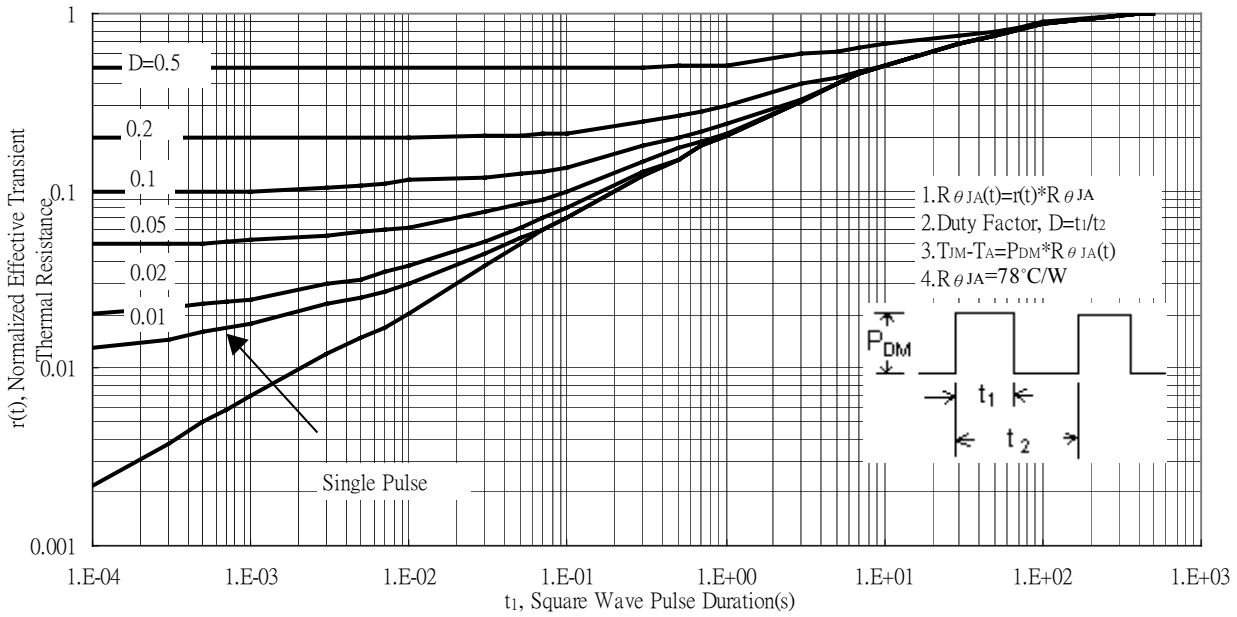
Typical Transfer Characteristics



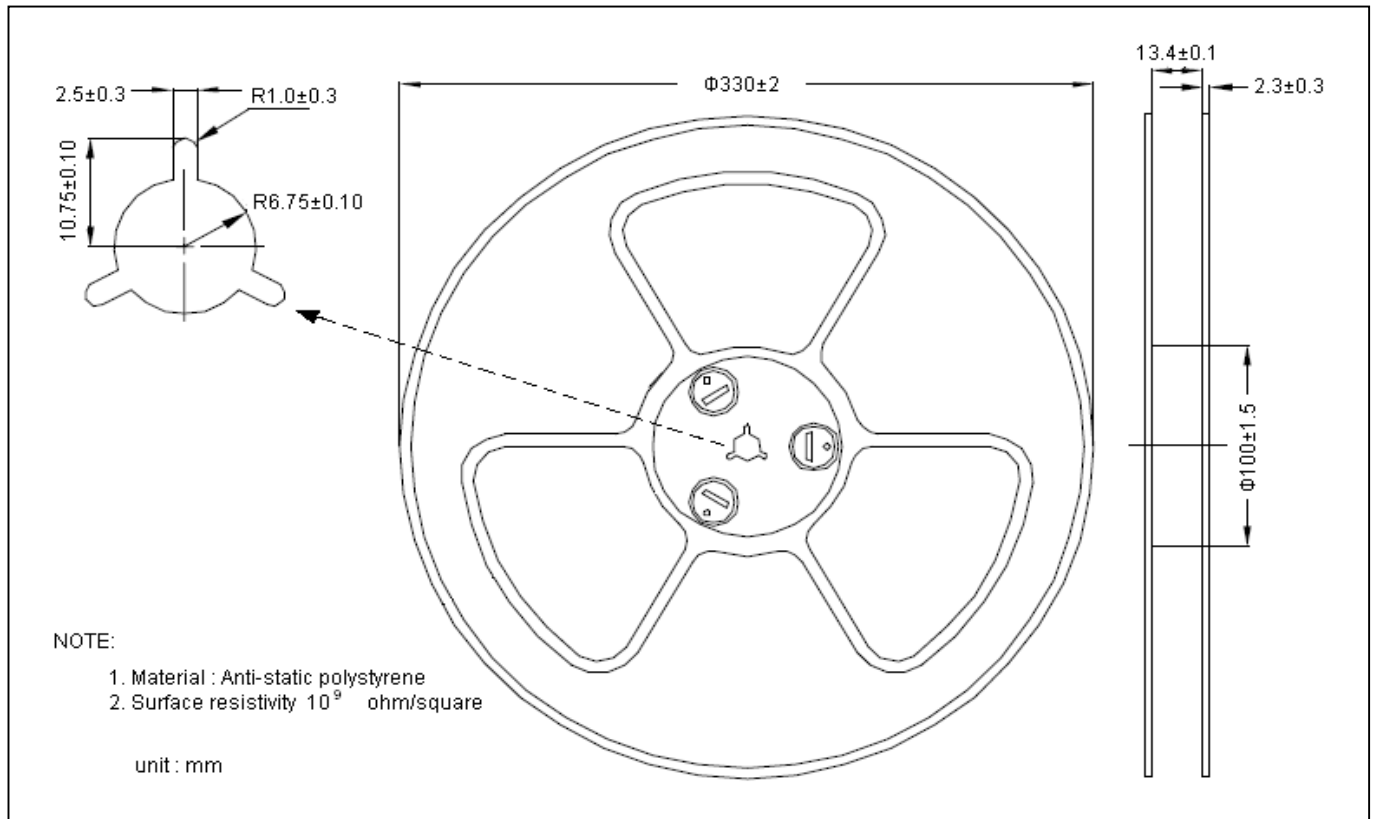
Single Pulse Power Rating, Junction to Ambient



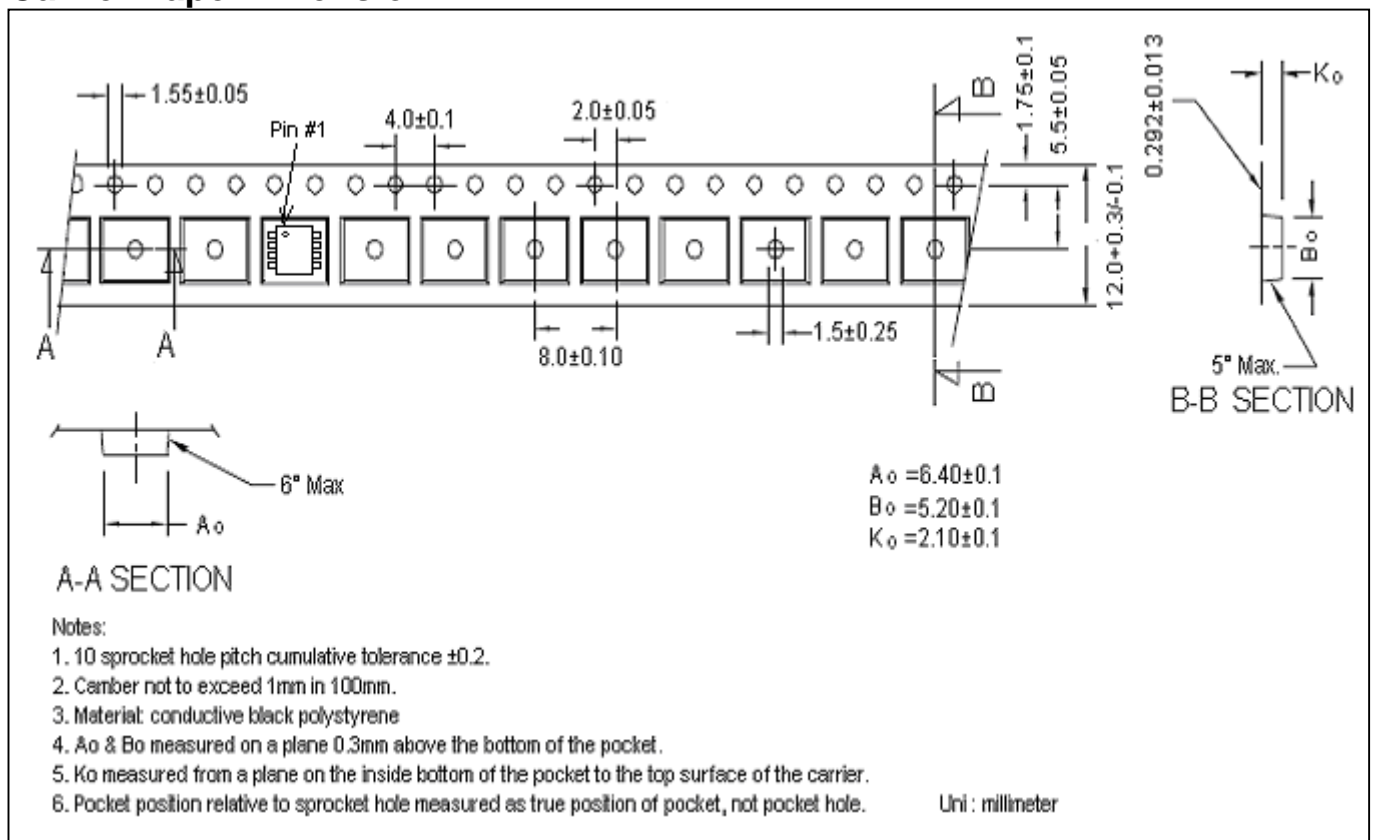
Transient Thermal Response Curves



Reel Dimension



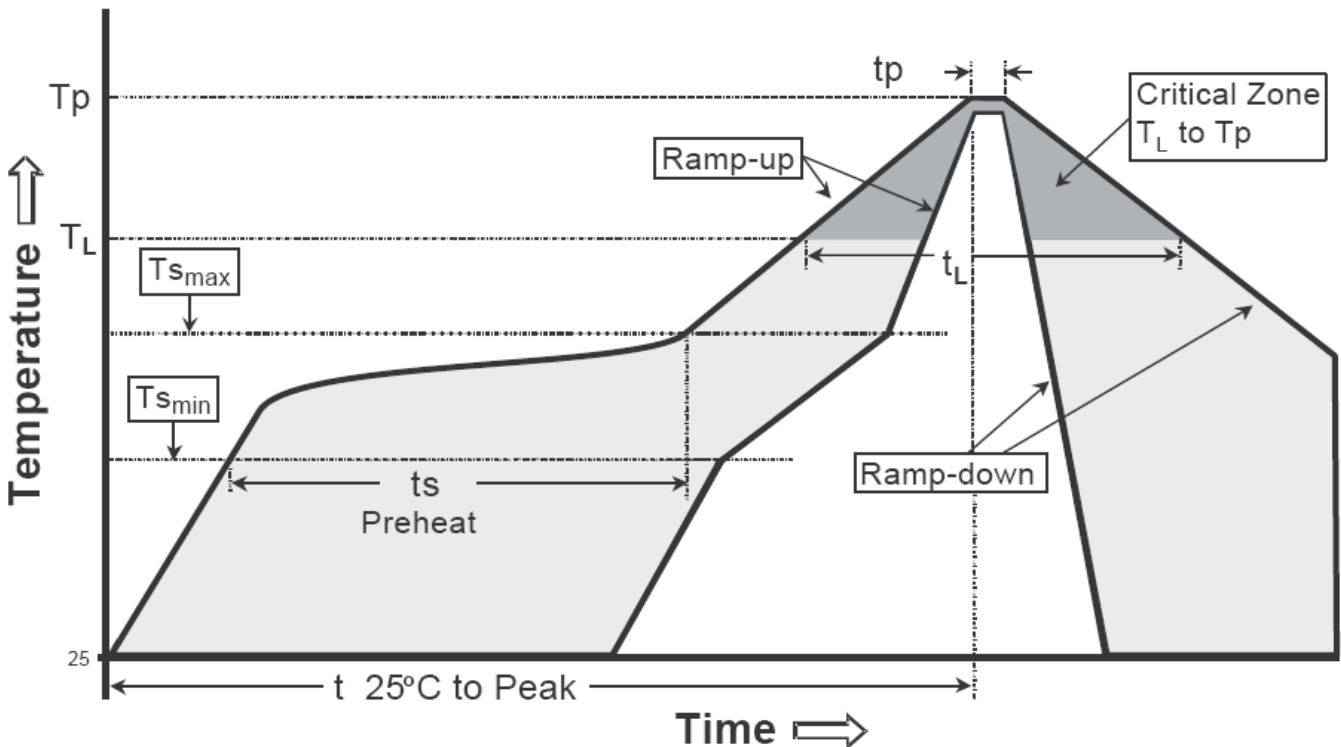
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

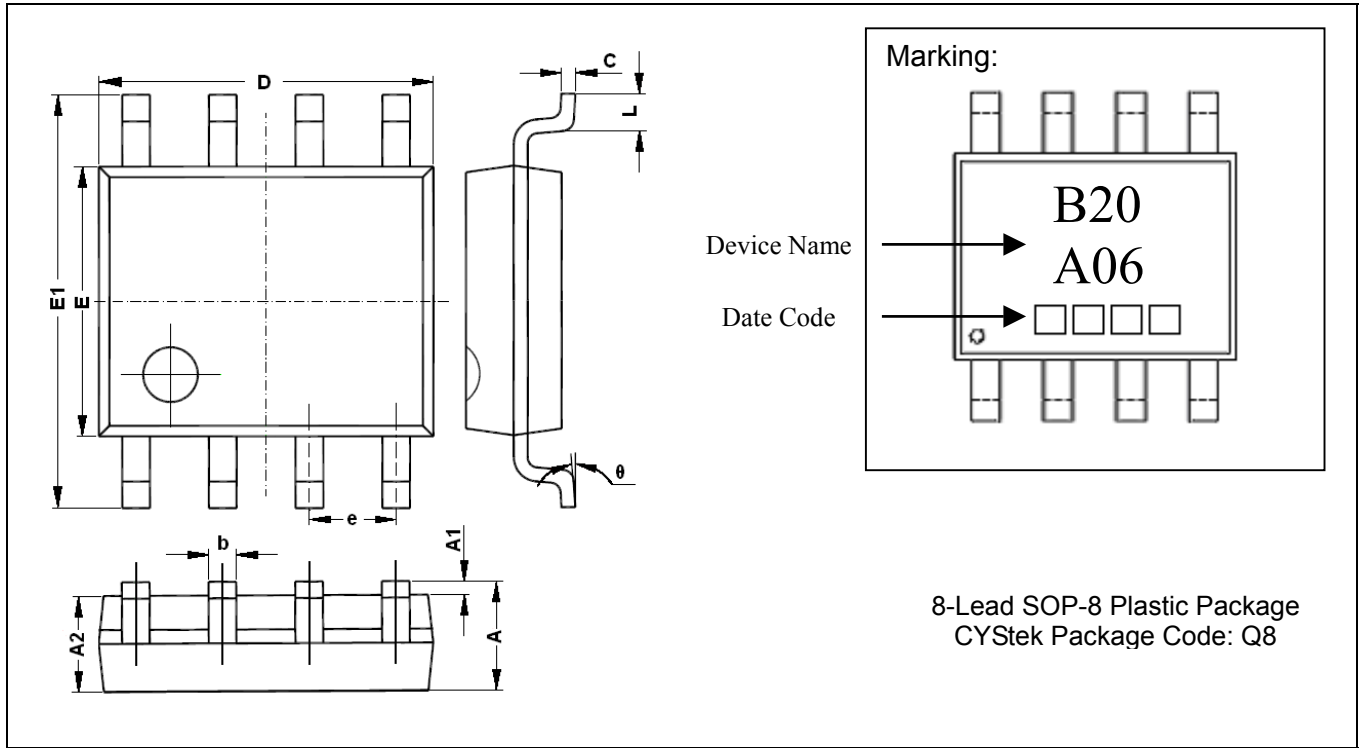
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (TL)	183°C	217°C
- Time (tL)	60-150 seconds	60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOP-8 Dimension



DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069	E	3.800	4.000	0.150	0.157
A1	0.100	0.250	0.004	0.010	E1	5.800	6.200	0.228	0.244
A2	1.350	1.550	0.053	0.061	e	1.270	(BSC)	0.050	(BSC)
b	0.330	0.510	0.013	0.020	L	0.400	1.270	0.016	0.050
c	0.170	0.250	0.006	0.010	θ	0	8°	0	8°
D	4.700	5.100	0.185	0.200					

Notes: 1. Controlling dimension: millimeters.
 2. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3. If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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